

Abstract

A thermal test head for an integrated circuit device includes a heat exchanger assembly, a contact assembly configured to contact the integrated circuit, and a thermal control assembly disposed between the heat exchanger assembly and the contact assembly. The thermal control assembly includes a Peltier device in thermal contact with opposing surfaces of the heat exchanger assembly and the contact assembly, and a spacer in physical contact with the opposing surfaces of the heat exchanger assembly and the contact assembly.

FIG. 1